









Release Date: 20 June 2017 Version: A1.0

PRODUCT DATASHEET



- ► PLCC2 SMD
- ➤ 3528 1.85t Series
- ▶ Blue (470nm)

N0B18S73



3528 1.85t Series





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APPLICATIONS:

- **Decoration Light**
- Indicator
- Switch Lights

- Package: PLCC2 White Top View SMD Package
- Forward Current: 20mA Forward Voltage (typ.): 3.2V
- Luminous Intensity (typ.): 320mcd@20mA
- Colour: Blue

FEATURES:

- Wavelength: 470nm Viewing angle: 120°
- **Materials:**
 - Die: InGaN
 - Resin: Silicon (Water Clear)
 - L/T Finish: Ag
- Operating Temperature: -20~+80°C Storage Temperature: -30~+100°C
- **Grouping parameters:**
 - Forward Voltage
 - **Luminous Intensity**
 - **Dominant Wavelength**
- Soldering methods: IR Reflow Soldering
- Preconditioning: MSL3 according to J-STD020
- Packing: 8mm tape with 2000/reel, ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	30	mA
Pulse Forward Current (Duty 1/10 @10KHz)	I _{PF}	100	mA
Reverse Current @5V	I _R	50	μΑ
Power Dissipation	P _D	108	mW
Electrostatic Discharge (HBM)	ESD	500	V
Operating Temperature	T _{OPR}	-20~+80	°C
Storage Temperature	T _{STG}	-30~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

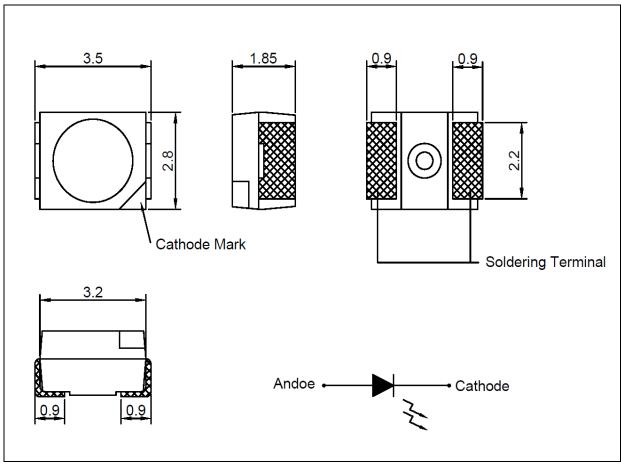
Parameter	Symbol		Values		Unit	Test
Parameter	Symbol	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V_{F}	2.8	3.2	3.6	V	I _F =20mA
Luminous Intensity	I _V	125	320	800	mcd	I _F =20mA
Dominant Wavelength	$\lambda_{ extsf{D}}$	465	470	477	nm	I _F =20mA
Spectral Line Half Bandwidth	Δλ		30		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

^{1.} Luminous intensity (I_V) $\pm 15\%$, Forward Voltage (V_F) $\pm 0.1V$, Viewing angle($2\theta_{1/2}$) $\pm 10^\circ$



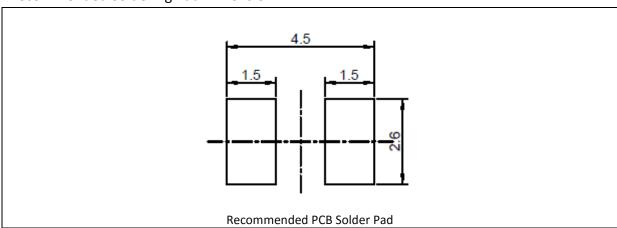
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
1	2.8	3.0	
2	3.0	3.2	V
3	3.2	3.4	V
4	3.4	3.6	

Luminous Intensity Classifications (I_F = 20mA):

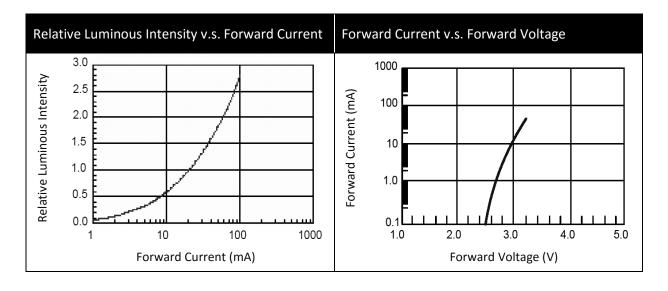
Code	Min.	Max.	Unit
R	125	200	
S	200	320	mad
Т	320	500	mcd
U	500	800	

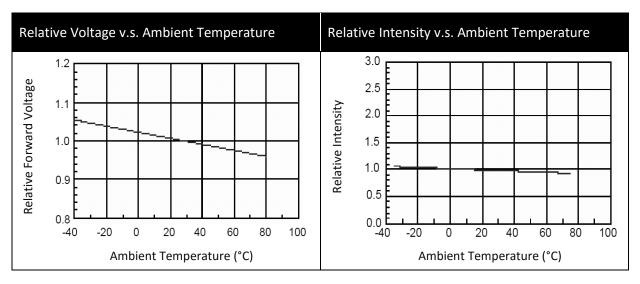
Dominant Wavelength Classifications ($I_F = 20$ mA):

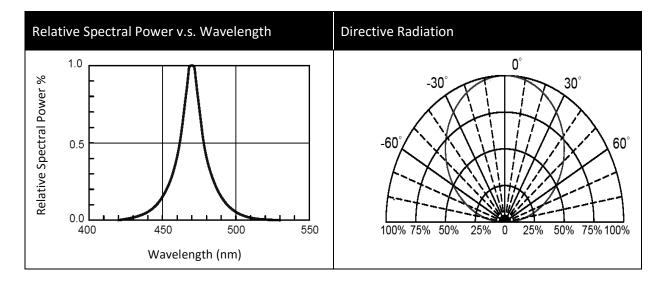
Code	Min.	Max.	Unit
0D	465	468	
0C	468	471	
OB	471	474	nm
0A	474	477	



ELECTRO-OPTICAL CHARACTERISTICS:



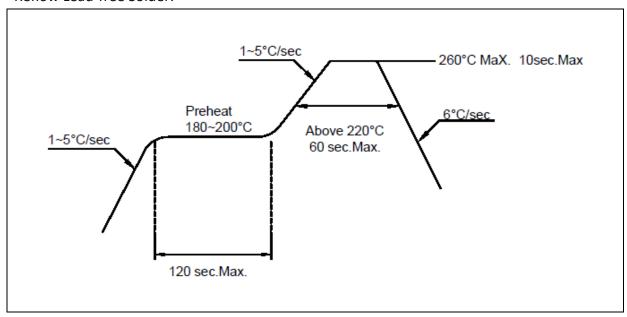






RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



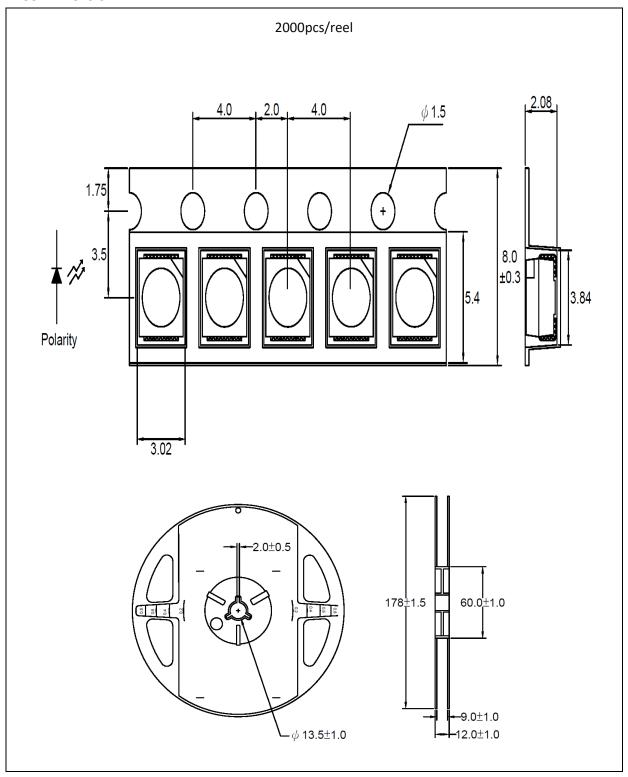
Note:

- 1. Maximum reflow soldering: 2 times.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

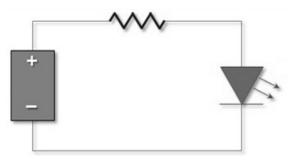
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 15hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	28/07/2015	Datasheet set-up.
A1.1	20/06/2017	Revise test condition.